

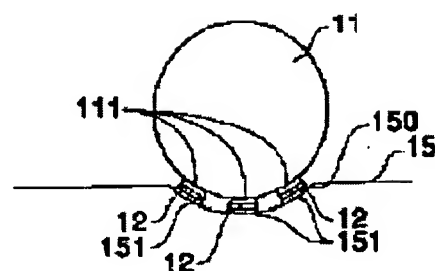
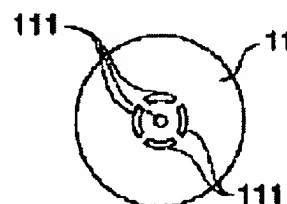
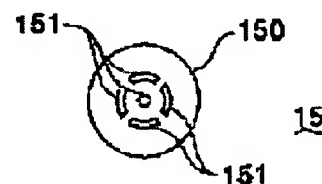
SEMICONDUCTOR DEVICE AND ITS MANUFACTURE**Publication number:** JP2000286296**Publication date:** 2000-10-13**Inventor:** UCHIYAMA KENJI**Applicant:** SEIKO EPSON CORP**Classification:****- international:** *H01L21/60; H01L23/485; H01L27/00; H01L29/06; H01L21/02; H01L23/48; H01L27/00; H01L29/02; (IPC1-7): H01L21/60***- European:** H01L21/60B2; H01L23/485B; H01L29/06C**Application number:** JP19990090011 19990330**Priority number(s):** JP19990090011 19990330**Also published as:**

US6573591 (B2)

US2002074655 (A1)

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PROBLEM TO BE SOLVED: To provide a semiconductor device which can positively electrically connect a spherical semiconductor and a substrate, and to provide its manufacture method. **SOLUTION:** In the substrate 15 of a semiconductor device 1, a recessed part 150 is formed in a region where a spherical semiconductor 11 is loaded and a terminal 151 is formed in the recessed part 150. When the spherical semiconductor 11 is arranged in the recessed part 150 and micro vibration is added to the substrate 15, the prescribed part of the spherical semiconductor 11 turns downward and the terminal 111 of the spherical semiconductor 11 can be overlapped accurately with the terminal 151 of the substrate 15, since the centroid of the spherical semiconductor is biased.

(A)**(B)****(C)**

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